

CLAIMS.

a) 1. A microelectronic element comprising:
 (a) a body defining a front surface, said body having pads exposed at said front surface;

 (b) flexible leads having pad ends and tip ends, said pad ends of said flexible leads being connected to said pads, said tip ends of at least some of said flexible leads projecting over said front surface of said body, said flexible leads being spaced apart from said front surface, said tip ends of said flexible leads being independently movable with respect to said body.

2. A microelectronic element as claimed in claim 1 wherein each said flexible lead is supported only at a pad connected to said flexible lead, and wherein each said flexible lead extends as a cantilever beam over said front surface of said body.

3. A microelectronic element as claimed in claim 1 wherein each said flexible lead is curved in a plane parallel to said front surface of said body.

4. A microelectronic element as claimed in claim 1 wherein each of said at least some of said flexible leads includes an elongated, striplike main region having substantially flat main surfaces, a first main surface facing toward said body, a second main surface facing away from said body.

5. A microelectronic element as claimed in claim 4 wherein each said main region extends generally parallel to said front surface of said body.

6. A microelectronic element as claimed in claim 4 wherein each of said at least some of said flexible leads includes at least one section disposed near to said front surface and at least one section remote from said front surface.

7. A microelectronic element as claimed in claim 6 wherein said at least one section remote from said front

~~surface constitutes said tip of said each of said at least some of said flexible leads.~~

8. A microelectronic element as claimed in claim 1 wherein said body includes at least one semiconductor chip.

9. A microelectronic element as claimed in claim 8 wherein each said semiconductor chip comprises a central region and a peripheral region surrounding said central region and wherein at least some of said pads are disposed in said peripheral region of each said semiconductor chip, said tip ends of said at least some of said flexible leads extending inwardly over said central region of each said semiconductor chip.

10. A microelectronic element as claimed in claim 9 wherein said body is a unitary semiconductor wafer including a plurality of semiconductor chips.

11. A microelectronic element as claimed in claim 1 wherein said body is a wafer probe card.

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